T-Global Technology Co., Ltd.

2026 Innovation Cultivation Program

Program Mission

As electrification and high-performance engineering accelerate, thermal management has become a critical foundation of modern mobility. With over 13 years of thermal expertise, T-Global Technology delivers precision-driven solutions that power performance-focused industries.

Our commitment goes beyond sponsorship. By connecting industry expertise with student innovation, we empower emerging engineers to experiment boldly, solve real-world challenges, and push the limits of performance through hands-on research and development. Rooted in deep campus engagement and industry–academia collaboration, T-Global is dedicated to cultivating future talent and advancing the thermal technologies that will shape tomorrow’s automotive and mobility landscape.

Program Objectives

This program aims to:

- Encourage innovative research among university students
- Promote industry–academia collaboration
- Support experiments, research projects, and academic papers related to thermal management topics

Eligibility

Students currently enrolled in degree programs that are accredited or officially recognized by the relevant authority in their country of origin, **regardless of field of study.**

Application Process

Thermal Interface Material Support

Application Period: Open year-round throughout 2026

For experimental needs from relevant academic departments, and provided that the delivery address is the department office of a college or university, applicants should refer to the T-Global website, complete the application form (Appendix 1) with the required information, and submit it to the designated contact email address. Please include a copy of the Sponsorship Package. T-Global will review the application and notify applicants of the review results within **fifteen** business days.

Official Website: http://www.tglobalcorp.com.tw/

Deliverables & Outcome Submission

- Upon completion of the research project, applicants must submit **Appendix 2**.
- All submissions must be sent via email with the subject line:
  [Innovation Cultivation Project_Research Outcome – University / Name]
- Please submit all required materials to the designated contact person:
  Ms. Ruby Wu
  Email: Ruby-Wu@tglobalcorp.com
  Submission will be considered complete upon receipt of the email.

Project Phase	Required Content
Pre-research phase	Group photo of all project members (2 photos)
Mid-research phase	Research progress photos (2–4 photos)
Post-research phase	Research outcome photos (2–4 photos)

Image Usage Authorization

By submitting the above materials, applicants grant **T-Global Technology Co,. Ltd.** the right to use the provided images for promotional and communication purposes. The submitted materials may be edited and published in official publications related to the **Innovation Cultivation Program**, including but not limited to program news features and reports.

Contact Hours (GMT+8): Monday to Friday, 9:30–12:00 and 13:00–17:00
Contact Person:

Ms. Wu, Marketing Department
(+886) 3-361-8899 #758
Ruby-Wu@tglobalcorp.com

**T-Global Technology Co., Ltd. reserves the right of final interpretation of this program.*

Appendix 1. Thermal Interface Material Support Application

Applicant Information			
First Name		Last Name	
Email Address			
Institution/University			
Program/ Department			
Expected Graduation Year			
Proof of Student Status			
Applicants must provide valid proof of current student status to confirm eligibility for participation in the program. (e.g., student ID, enrollment certificate, or official registration record for the current academic year).			
Research Objective			
Thermal Interface Materials (TIM) Requirements			
Product Name.			
Link to Product			
Quantity (ml/g/kg)		Size (L *W* T mm)	
Additional Notes/ Remarks:			
Shipping Information			
Full Name			
Address			
Country		Postal Code/ZIP Code	
Phone			

By submitting this application, I confirm that the information provided is accurate to the best of my knowledge and aligns with the educational purpose of this program.

Applicant Signature	**Date of Application**

Appendix 2. Program Feedback Questionnaire

Applicant Information			
First Name		Last Name	
Email Address			
Feedback Questionnaire			

1. How did you first learn about this sponsorship project?

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2. What were the biggest obstacles that you encountered during your project? (Please respond in approximately 100 words.)

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3. How did T-Global's support benefit your project after you joined this subsidy program? (Please list three key benefits and provide a brief description for each.)

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4. How did the product(s) perform in supporting your research or experimentation?

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5. Do you have any feedback or messages you would like to share with T-Global?

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6. Would you consider applying for a position at T-Global in the future?

☐ Yes ☐ No *(Please select Yes or No, and briefly explain your reason.)*

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7. Would you recommend this sponsorship project to other students at your university or college? ☐ Yes ☐ No *(Please select Yes or No, and briefly explain your reason.)*

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Thank you for completing the questionnaire. We appreciate your feedback.

Don’t forget to check out our fan page and give us a like! 👉